CLAIMS

1. A hollow electronic device sealing resin sheet, comprising a first resin layer and a second resin layer,

the first and second resin layers each comprising a filler, and

the resin sheet satisfying the following expressions (1) and (2):

"content (% by volume) of the filler in the first resin layer" < "content (% by volume) of the filler in the second resin layer" (1); and

"viscosity of the first resin layer" > "viscosity of the second resin layer" (2),

wherein the ratio of tensile storage elastic modulus of the first resin layer to tensile storage elastic modulus of the second resin layer (the value of "first resin layer tensile storage elastic modulus/"second resin layer tensile storage elastic modulus") is from 5 to 500.

2. The hollow electronic device sealing resin sheet according to claim 1, wherein the ratio of viscosity of the first resin layer to viscosity of the second resin layer (the value of "first resin layer viscosity"/"second resin layer viscosity") is from 3 to 1000.

~~3. The hollow electronic device sealing resin sheet according to claim 1 or 2, wherein the ratio of tensile storage elastic modulus of the first resin layer to tensile storage elastic modulus of the second resin layer (the value of "first resin layer tensile storage elastic~~

~~modulus/"second resin layer tensile storage elastic modulus") is from 5 to 500.~~

~~4~~3. The hollow electronic device sealing resin sheet according to ~~any one of~~ claim~~s~~ 1 or~~to~~ 2~~3~~, wherein the ratio of average particle diameter of the filler in the first resin layer to average particle diameter of the filler in the second resin layer (the value of "average particle diameter of the filler in the first resin layer"/"average particle diameter of the filler in the second resin layer") is from 0.01 to 0.5.

~~5~~4. The hollow electronic device sealing resin sheet according to any one of claims 1 to ~~4~~3, wherein the content of the filler in the first resin layer is 69% by volume or less, and the content of the filler in the second resin layer is more than 69% by volume.

~~6~~5. The hollow electronic device sealing resin sheet according to any one of claims 1 to ~~5~~4, wherein the ratio of thickness of the first resin layer to thickness of the second resin layer (the value of "first resin layer thickness"/"second resin layer thickness") is from 0.05 to 0.3.

~~7~~6. The hollow electronic device sealing resin sheet according to any one of claims 1 to ~~6~~5, wherein the viscosity of the first resin layer is 10000 Pa·s or more.

~~8~~7. A method for manufacturing a hollow electronic device package, comprising:

a~~the~~ step of providing the hollow electronic device sealing resin sheet recited in any one of claims 1 to ~~7~~6;

a~~the~~ step of providing a substrate on which a hollow electronic device is to be mounted; and

a~~the~~ step of laminating the hollow electronic device sealing resin sheet on the substrate to bring the first resin layer into contact with the hollow electronic device and the substrate.